Rev	Description	Appd.	Date
0	initial release	lag	01-03-00

Notes:

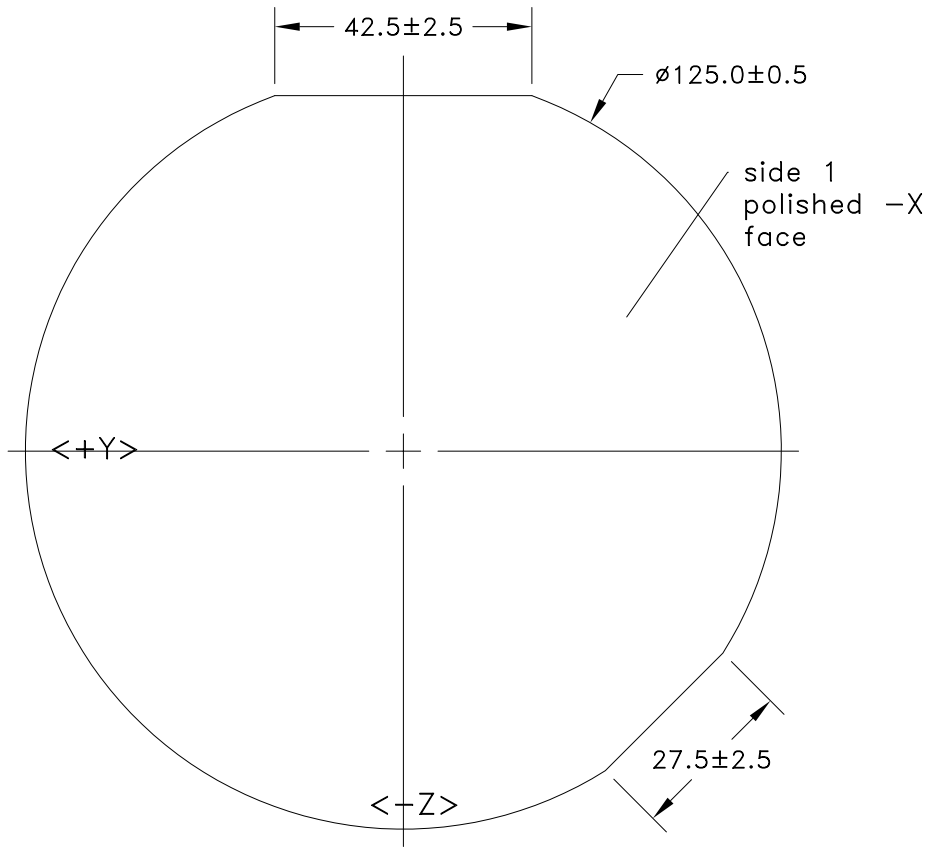
1.0 Orientations
- 1.1 Wafer surface is normal to <X> ±0.5°
- 1.2 Flats
  - 1.2.1 Primary flat is normal to <+Z> ±0.5°.
  - 1.2.2 Secondary flat is 135°±1° clockwise from the <+Z> flat when viewing the <−X> face.

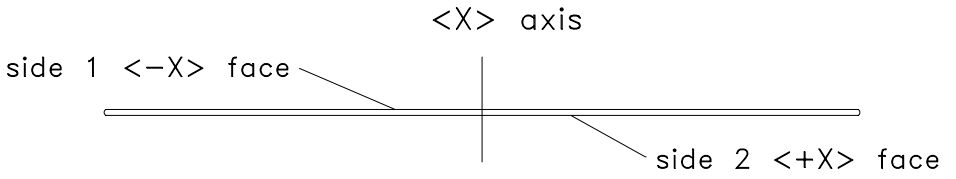
2.0 Edge
- 1.1 All edges rounded with R0.57 ±0.08mm.
- 1.2 No chips more than 0.5mm in penetration and 1.0mm in length.

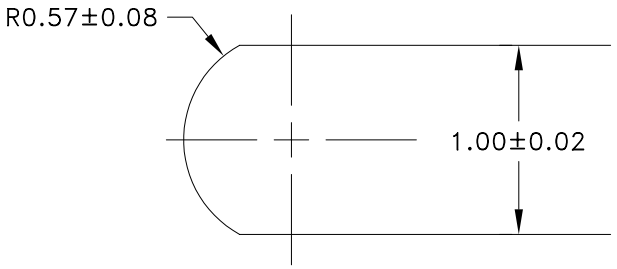
3.0 Surfaces
- 3.1 Side 1 <−X> face
  Polished 10−5 scratch−dig with 1mm edge exclusion.
  Inspected with reflected light and unaided eye.
- 3.2 Side 2 <+X> face
  Polished 60−30 scratch−dig with 1mm edge exclusion.
  Inspected with reflected light and unaided eye.

4.0 Flatness
- 4.1 Warp < 50µm.
- 4.2 TTV < 25µm.

For Reference Only







Wafer Edge Detail, 25X

Material: Lithium Niobate	DR.	Igordon	01-03-00
Unless otherwise specified, dimensions in mm	CHK.		
Tolerances	APPD.		
Inches: .X ± 0.1, .XX ± 0.01, .XXX ± 0.005, .XXXX ± 0.0020 / Millimeters: X ± 0.5, .X ± 0.25, .XX ± 0.1, .XXX ± 0.05	Wafer Code:		
Angles ± 0.5°	Customer Approval:		
DO NOT SCALE DRAWING			

Crystal Technology, Inc.
An EPCOS Company

Title: LNIO 125ø x 1.0mm, <−X> Po/Po, +Z FLT

Size: A | Dwg. No: 97-02604-01 | Rev: A

Scale: 0.8:1 | Sheet 1 of 1